**ZHONGFA AVIATION UNIVERSITY**

**Academic Position Application Form**

(Please send the application form to zhongfa@vip.sina.com)

|  |  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- | --- |
| **SURNAME** |  | **GIVEN NAME(S)** |  | **GENDER** |  | **DATE OF BIRTH** |  |
| **NATIONALITY** |  | **TELEPHONE** |  | **EMAIL ADDRESS**  |  |
| **CURRENT AFFILIATION** |  | **CURRENT ACADEMIC TITLE** |  |
| **SCHOOL APPLIED FOR** |  | **FIELD OF STUDY APPLIED FOR** | **Please choose among the following fields of study ①** |
| **APPLIED POSITION** | **Please choose among the following positions ②** | **FUNDING PROGRAMME(S)** |  |
| **EDUCATION &WORK EXPERIENCES (CONTINUOUS, STARTING FROM UNDERGRADUATE STUDY)** |
| TIME | AFFILIATION | DEGREE/ SPECIALIZATION/ POSITION |
| mm/yyyy-mm/yyyy | e.g.: MIT | e.g. Ph.D., Aerospace Engineering |
| **A BRIEF INTRODUCTION OF YOUR RESEARCH CAPABILITY AND SPECIALIZATIONS**(within 1000 words) |  |
| **RESEARCH PAPER** |
| TITLE | JOURNAL/ CONFERENCE | TIME OF PUBLICATION | CITATION | IMPACT FACTOR | Q INDEX & RANKING | AUTHOR RANKING |
| (If not, delete this row and the header) | e.g. Advanced Materials | e.g. May, 2013 | e.g. SCI/69 times | e.g. 15.409(the latest data of JCR) | e.g. Q1, 6/251 (Material Science) | e.g. first author |
| **MONOGRAPH** |
| TITLE | PUBLISHER | TIME OF PUBLICATION | WORD COUNT: CONTRIBUTED/ TOTAL | RANKING |
| (If not, delete this row and the header) |  |  |  | e.g. 1/4 |
| **AWARD** |
| AWARD NAME | TITLE | TIME  | AWARDING AUTHORITY | LEVEL | RANKING |
| (If not, delete this row and the header) |  |  |  |  | e.g. 1/3 |
| **PATENT** |
| PATENT NAME | PATENT TYPE | APPROVAL TIME | APPROVAL AGENCY | PATENT NO. | RANKING |
| (If not, delete this row and the header) |  |  |  |  | e.g. 1/2 |
| **RESEARCH FUNDING PROGRAMME** |
| PROGRAMME NAME | SOURCE OF FUNDING | TIME | RECEIVED / TOTAL AMOUNT |
| (If not, delete this row and the header) |  |  |  |
| OTHER(within 1000 words) |  |
| **I hereby declare that the information provided is true and correct, and I take full responsibility for any false information and the pursuant consequences. Signature： Date：** |

1. **School of Civil Aviation:** space-air-ground integrated network and aeronautical broadband communication, air traffic management and transportation planning, avionics and satellite navigation, general aviation and intelligent operations, and civil aviation finance and regulations.

**School of Aerospace:** trans-sonic aviation aerodynamics and thermodynamics, green aviation and alternative aviation fuels (AAFs), aerospace big data and its environmental and climatic implications, and unmanned/manned general aviation and unconventional aerospace engineering.

**School of Informatics:** quantum precision measurement, high-performance quantum computation, artificial intelligence, integrated circuit materials and devices, electronic design automation of integrated circuits, aviation microelectronics, and control science and engineering.

**School of Engineering:** high-temperature/ultra-high-temperature materials, high-temperature functional coating, high-temperature corrosion, advanced lightweight materials, advanced composite materials, new energy materials, optoelectronic materials, digital design and manufacturing integration technology, carbon fiber composites manufacturing process, and robot design and control technology.

**School of Science:** new state of quantum matter, extreme condition physics, and medical physics.

1. **Open positions:** Chair Professor, Tenured Associate Professor, Tenure-track Associate Professor, Assistant Professor, Postdoctoral Fellow